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Gold/Aluminum Wedge Bonder 6400

The new 6400 family of machines has been developed from F&K Delvotec's highly successful, production proven 6300 series of rotary head bonders and offers the best choice for a wide range of commercially and strategically important applications. Linear-motor-drive-systems ensure fast, smooth-running operation with unprecedented accuracy and repeatability in a small footprint mainframe

- X/Y/Z and theta motion contained in the head enables rigid clamping of device and simpler design of automatic handling systems
- Pentium™ processor with UNIX™ based operating system and full network capability
- The basic machine is configured for an 200" x 150" bond area
- All machines include the BPC 2000, F&K Delvotec's patented on-line bond process control unit for highest quality, repeatable bonds
- All machines use a process tolerant, grey-level pattern recognition system from Cognex
- Red and white light sources available with direct, oblique and diffuse lighting
- Programmable piezo-technology controlled wire clamp unit leads to better process control
- Programmable bondweight controlled by linear motor system
- Over 10,000 wires and 200 dice in a single program
- Step and repeat capability for modular programming Component handling can be manual, semi-automatic, fully automatic magazine-to-magazine or with an in-line link to conveyor systems

The family concept with a common hardware and software base allows retrofit of all options at any time but keeps the cost of the initial investment down to an absolute minimum

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